SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and Outputs
- Distributes One Clock Input to Eight Outputs
- Distributed V_{CC} and Ground Pins Reduce Switching Noise
- High-Drive Outputs (-48-mA I_{OH}, 48-mA I_{OL})
- State-of-the-Art EPIC-IIB™ BiCMOS Design
 Significantly Reduces Power Dissipation
- Packaging Options Include Plastic
 Small-Outline (DW) Packages

(TOP VIEW)							
V _{CC}	1	20	Vcc				
V _{CC} [1G [2	19	V _{CC}				
2G [3	18	1Y2				
Α [4	17] GND				
P0 [5	16	1Y3				
P1 [6	15	1Y4				
V _{CC} [2Y4 [7	14] GND				
	8	13	2Y1				
2Y3 [9	12	2Y2				
GND [10	11] GND				

description

The CDC341 is a high-performance clock-driver circuit that distributes one (A) input signal to eight (Y) outputs with minimum skew for clock distribution. Through the use of the control pins (1G and 2G), the outputs can be placed in a low state regardless of the A input.

The propagation delays are adjusted at the factory using the P0 and P1 pins. These pins are not intended for customer use and should be strapped to GND.

The CDC341 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

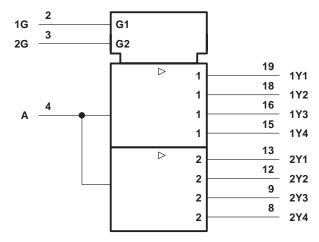
INPUTS			OUTPUTS			
1G	2G	Α	1Y1-1Y4	2Y1-2Y4		
Х	Х	L	To L'or	L		
L	L	Н	V/L	L		
L	Н	Н		Н		
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Н	Н	Н	Н	Н		

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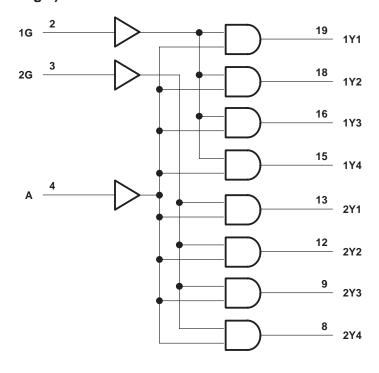


logic symbol†



 $[\]ensuremath{^{\dagger}}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state,	
V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, I _O	
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		4.75	5.25	V
VIH	H High-level input voltage				V
V _{IL}	Low-level input voltage			0.8	V
VI	Input voltage				V
IOH	High-level output current			-48	mA
loL	Low-level output current			48	mA
f	Input clock frequency	One output bank loaded		80	MHz
fclock	Both output banks loaded			40	IVITIZ
TA	Operating free-air temperature		0	70	°C

NOTE 3: Unused pins (input or I/O) must be held high or low.

CDC341 1-LINE TO 8-LINE CLOCK DRIVER

SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			MIN	MAY	UNIT	
PARAIVIETER	'	EST CONDITIONS		MIN	TYP†	MAX	MIN MAX		UNIT
VIK	$V_{CC} = 4.75 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2		-1.2	V
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		
Voн	$V_{CC} = 5 V$	$I_{OH} = -3 \text{ mA}$		3			3		V
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -48 \text{ mA}$		2			2		
VOL	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 48 \text{ mA}$						0.5	V
lį	$V_{CC} = 5.25 \text{ V},$	$V_I = V_{CC}$ or GND				±1		±1	μΑ
1 ₀ ‡	$V_{CC} = 5.25 \text{ V},$	$V_0 = 2.5 \text{ V}$		-50	-100	-200	-50	-200	mA
loo	V _{CC} = 5.25 V,	I _O = 0,	Outputs high		2			3.5	mA
lcc	$V_I = V_{CC}$ or GND		Outputs low		24			33	IIIA
C _i	V _I = 2.5 V or 0.5 V				3				pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

switching characteristics, C_L = 50 pF (see Figures 1 and 2)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			V _{CC} = 4.75 T _A = 0°	UNIT	
	(INPUT)		MIN	TYP	MAX	MIN	MAX	
^t PLH	A	V	3.5		4.5	3.1	4.9	no
t _{PHL}	A	T	3.5		4.3	3.1	4.9	ns
^t PLH	G	V	2		3.8	2	4	20
tPHL]	T	2		3.8	2	4	ns
t _{sk(o)}				0.3	0.5		0.6	
t _{sk(p)}	A	Y		0.6	0.8		0.9	ns
^t sk(pr)					1		1	
t _r	А	Υ					1.5	ns
t _f	А	Υ					1.5	ns

$t_{\mbox{\scriptsize pd}}$ performance information relative to $V_{\mbox{\scriptsize CC}}$ and temperature variation (see Note 4)

Dt _{PLH(TA)} †	Temperature drift of tpLH from 0°C to 70°C	-41 ps/10°C
Dt _{PHL(TA)} †	Temperature drift of tpHL from 0°C to 70°C	−52 ps/10°C
DtpLH(VCC) [‡]	V _{CC} drift of t _{PLH} from 4.75 V to 5.25 V	28 ps/100 mV
Dt _{PHL(VCC)} ‡§	V _{CC} drift of t _{PHL} from 4.75 V to 5.25 V	20 ps/100 mV

[†] Virtually independent of V_{CC}

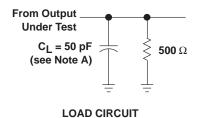
NOTE 4: The data extracted is from a wide range of characterization material.

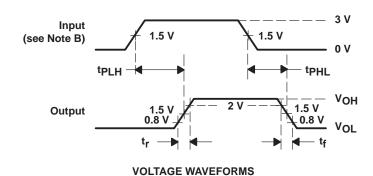


[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[‡] Virtually independent of temperature

PARAMETER MEASUREMENT INFORMATION



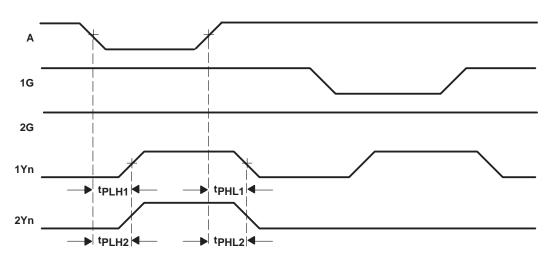


NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.

Figure 1. Load Circuit and Voltage Waveforms

PROPAGATION DELAY TIMES



NOTES: A. Output skew, $t_{Sk(O)}$, is calculated as the greater of:

- The difference between the fastest and slowest of tpLHn (n = 1, 2)
- The difference between the fastest and slowest of t_{PHLn} (n = 1, 2)
- B. Pulse skew, $t_{Sk(p)}$, is calculated as the greater of $|t_{PLHn} t_{PHLn}|$ (n = 1, 2).
- C. Process skew, $t_{sk(pr)}$, is calculated as the greater of:
 - The difference between the fastest and slowest of tpLHn (n = 1, 2) across multiple devices under identical operating conditions
 - The difference between the fastest and slowest of tpHLn (n = 1, 2) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of $t_{sk(0)}$, $t_{sk(p)}$, $t_{sk(pr)}$



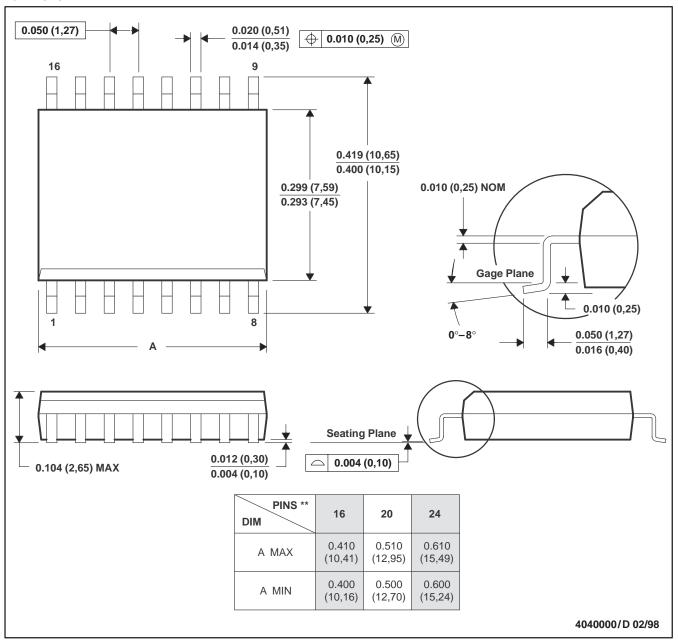
SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

MECHANICAL INFORMATION

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



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